

AMENDMENTS TO THE CLAIMS

1. (Original) A method for electroless deposition of a metal onto a substrate, said substrate comprising polyimide exposed at a surface thereof, the method comprising:

electroless depositing a metal onto the substrate by applying a solution comprising a metal source, a reducing agent, an additive to adjust the pH of the solution to a predetermined value and an aromatic sulfonic acid.

2. (Original) A method according to claim 1, wherein the aromatic sulfonic acid comprises a sulfonic acid, an aromatic group and an apolar chain.

3. (Original) A method according to claim 1, further comprising exposing the surface to an anti-drag-through agent.

4. (Original) A method according to claim 1, the method furthermore comprising activating the substrate by applying a solution comprising a colloidal catalyst.

5. (Original) A method according to claim 4, wherein the colloidal catalyst includes Pd.

6. (Original) A method according to claim 4 wherein the colloidal catalyst includes Sn.

7. (Original) A method according to claim 4 wherein the colloidal catalyst is colloidal Pd/Sn.

8. (Original) A method according to claim 4, further comprising applying a solution comprising an accelerator.

9. (Original) A method according to claim 7, further comprising applying a solution comprising an accelerator.

10. (Original) A method according to claim 1, the method furthermore comprising a preliminary step of cleaning a surface of the substrate.

11. (Original) A method according to claim 1, the method furthermore comprising:

applying an anti-tarnish solution; and
baking.

12. (Original) A method according to claim 1, wherein depositing a metal comprises depositing copper.

13. (Original) A method according to claim 1, wherein the substrate is flexible.

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14. (Original) A method according to claim 1, wherein the substrate is a polyimide substrate.

15. (Original) A method according to claim 1, wherein the substrate comprises through holes or vias.

16. (Original) A plating bath for electroless deposition of a metal onto a substrate, the substrate comprising polyimide exposed at a surface thereof, the plating bath comprising a solution comprising a metal source, a reducing agent, an additive to adjust the pH of the solution to a predetermined value and an aromatic sulfonic acid.

17. (Original) A plating bath according to claim 16 further comprising a substrate with polyimide exposed on at least one surface for electroless deposition of the metal.

18. (Original) A plating bath according to claim 16, wherein the metal source is copper.

19. (Original) A plating according to claim 16, wherein the aromatic sulfonic acid comprises a sulfonic acid, an aromatic group and an apolar chain.

20. (New) A method according to claim 1, wherein the substrate comprises through holes or vias, and wherein the step of electroless depositing a metal onto the substrate comprises electroless depositing a metal onto both sides of the substrate.

21. (New) A plating according to claim 16, further comprising a substrate with polyimide exposed on both surfaces of the substrate for electroless deposition of the metal, wherein the substrate comprises through holes or vias.